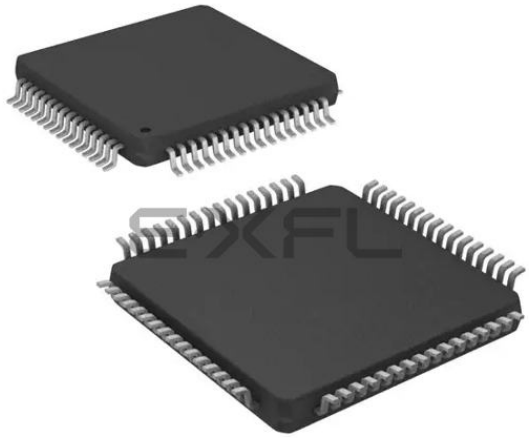

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Applications of "Embedded - Microcontrollers"

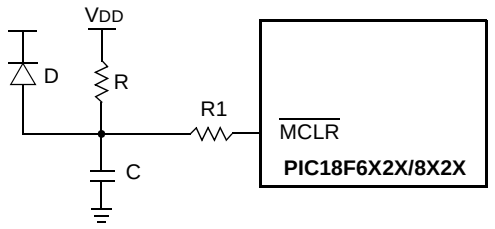
Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	25MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	53
Program Memory Size	48KB (24K x 16)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	3.75K x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f6525-e-pt

3.1 Power-on Reset (POR)

A Power-on Reset pulse is generated on-chip when VDD rise is detected. To take advantage of the POR circuitry, tie the MCLR pin through a 1 kΩ to 10 kΩ resistor to VDD. This will eliminate external RC components usually needed to create a Power-on Reset delay. A minimum rise rate for VDD is specified (parameter D004). For a slow rise time, see Figure 3-2.

When the device starts normal operation (i.e., exits the Reset condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in Reset until the operating conditions are met.

FIGURE 3-2: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



Note 1: External Power-on Reset circuit is required only if the VDD power-up slope is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.

2: R < 40 kΩ is recommended to make sure that the voltage drop across R does not violate the device's electrical specification.

3: R1 = 1 kΩ to 10 kΩ will limit any current flowing into MCLR from external capacitor C in the event of MCLR/VPP pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

3.2 Power-up Timer (PWRT)

The Power-up Timer provides a fixed nominal time-out (parameter 33) only on power-up from the POR. The Power-up Timer operates on an internal RC oscillator. The chip is kept in Reset as long as the PWRT is active. The PWRT's time delay allows VDD to rise to an acceptable level. A configuration bit is provided to enable/disable the PWRT.

The power-up time delay will vary from chip-to-chip due to VDD, temperature and process variation. See DC parameter 33 for details.

3.3 Oscillator Start-up Timer (OST)

The Oscillator Start-up Timer (OST) provides a 1024 oscillator cycle (from OSC1 input) delays after the PWRT delay is over (parameter 32). This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset, or wake-up from Sleep.

3.4 PLL Lock Time-out

With the PLL enabled, the time-out sequence following a Power-on Reset is different from other oscillator modes. A portion of the Power-up Timer is used to provide a fixed time-out that is sufficient for the PLL to lock to the main oscillator frequency. This PLL lock time-out (TPLL) is typically 2 ms and follows the oscillator start-up time-out.

3.5 Brown-out Reset (BOR)

A configuration bit, BOR, can disable (if clear/programmed) or enable (if set) the Brown-out Reset circuitry. If VDD falls below parameter D005 for greater than parameter 35, the brown-out situation will reset the chip. A Reset may not occur if VDD falls below parameter D005 for less than parameter 35. The chip will remain in Brown-out Reset until VDD rises above BVDD. If the Power-up Timer is enabled, it will be invoked after VDD rises above BVDD; it then will keep the chip in Reset for an additional time delay (parameter 33). If VDD drops below BVDD while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be initialized. Once VDD rises above BVDD, the Power-up Timer will execute the additional time delay.

3.6 Time-out Sequence

On power-up, the time-out sequence is as follows: First, PWRT time-out is invoked after the POR time delay has expired. Then, OST is activated. The total time-out will vary based on oscillator configuration and the status of the PWRT. For example, in RC mode with the PWRT disabled, there will be no time-out at all. Figure 3-3, Figure 3-4, Figure 3-5, Figure 3-6 and Figure 3-7 depict time-out sequences on power-up.

Since the time-outs occur from the POR pulse, the time-outs will expire if MCLR is kept low long enough. Bringing MCLR high will begin execution immediately (Figure 3-5). This is useful for testing purposes or to synchronize more than one PIC18F6525/6621/8525/8621 device operating in parallel.

Table 3-2 shows the Reset conditions for some Special Function Registers, while Table 3-3 shows the Reset conditions for all of the registers.

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REGISTER 4-2: STKPTR: STACK POINTER REGISTER

R/C-0	R/C-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
STKFUL(1)	STKUNF(1)	—	SP4	SP3	SP2	SP1	SP0
bit 7							bit 0

bit 7 **STKFUL:** Stack Full Flag bit(1)
1 = Stack became full or overflowed
0 = Stack has not become full or overflowed

bit 6 **STKUNF:** Stack Underflow Flag bit(1)
1 = Stack underflow occurred
0 = Stack underflow did not occur

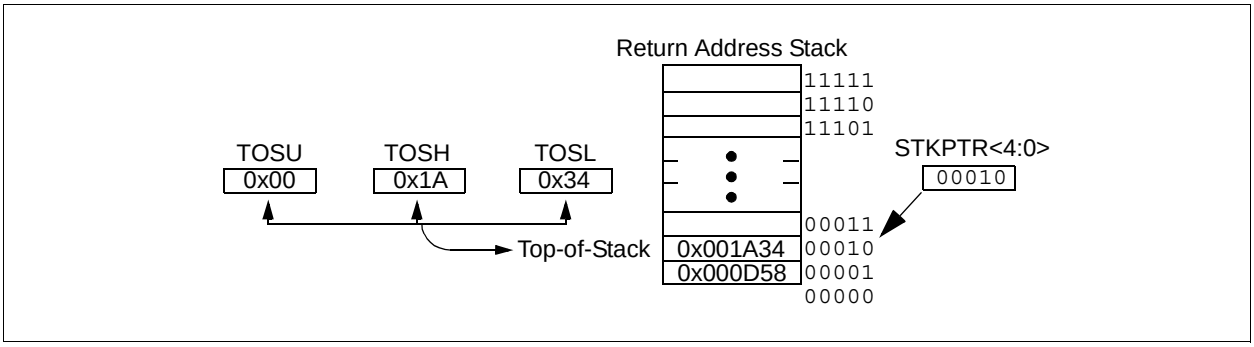
bit 5 **Unimplemented:** Read as '0'

bit 4-0 **SP4:SP0:** Stack Pointer Location bits

Note 1: Bit 7 and bit 6 can only be cleared in user software or by a POR.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

FIGURE 4-4: RETURN ADDRESS STACK AND ASSOCIATED REGISTERS



4.2.3 PUSH AND POP INSTRUCTIONS

Since the Top-of-Stack (TOS) is readable and writable, the ability to push values onto the stack and pull values off the stack, without disturbing normal program execution, is a desirable option. To push the current PC value onto the stack, a PUSH instruction can be executed. This will increment the Stack Pointer and load the current PC value onto the stack. TOSU, TOSH and TOSL can then be modified to place a return address on the stack.

The ability to pull the TOS value off of the stack and replace it with the value that was previously pushed onto the stack, without disturbing normal execution, is achieved by using the POP instruction. The POP instruction discards the current TOS by decrementing the Stack Pointer. The previous value pushed onto the stack then becomes the TOS value.

4.2.4 STACK FULL/UNDERFLOW RESETS

These Resets are enabled by programming the STVREN configuration bit. When the STVREN bit is disabled, a full or underflow condition will set the appropriate STKFUL or STKUNF bit, but not cause a device Reset. When the STVREN bit is enabled, a full or underflow condition will set the appropriate STKFUL or STKUNF bit and then cause a device Reset. The STKFUL or STKUNF bits are only cleared by the user software or a Power-on Reset.

REGISTER 9-12: IPR3: PERIPHERAL INTERRUPT PRIORITY REGISTER 3

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	RC2IP	TX2IP	TMR4IP	CCP5IP	CCP4IP	CCP3IP
bit 7							bit 0

bit 7-6 **Unimplemented:** Read as '0'

bit 5 **RC2IP**: USART2 Receive Interrupt Priority bit
1 = High priority
0 = Low priority

bit 4 **TX2IP**: USART2 Transmit Interrupt Priority bit
1 = High priority
0 = Low priority

bit 3 **TMR4IP**: TMR4 to PR4 Match Interrupt Priority bit
1 = High priority
0 = Low priority

bit 2-0 **CCPxIP**: CCPx Interrupt Priority bit (ECCP3, CCP4 and CCP5)
1 = High priority
0 = Low priority

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

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TABLE 10-1: PORTA FUNCTIONS

Name	Bit#	Buffer	Function
RA0/AN0	bit 0	TTL	Input/output or analog input.
RA1/AN1	bit 1	TTL	Input/output or analog input.
RA2/AN2/VREF-	bit 2	TTL	Input/output, analog input or VREF-.
RA3/AN3/VREF+	bit 3	TTL	Input/output, analog input or VREF+.
RA4/T0CKI	bit 4	ST	Input/output or external clock input for Timer0. Output is open-drain type.
RA5/AN4/LVDIN	bit 5	TTL	Input/output, analog input or Low-Voltage Detect input.
OSC2/CLKO/RA6	bit 6	TTL	OSC2, clock output or I/O pin

Legend: TTL = TTL input, ST = Schmitt Trigger input

TABLE 10-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
PORTA	—	RA6(1)	RA5	RA4	RA3	RA2	RA1	RA0	-x0x 0000	-u0u 0000
LATA	—	LATA6(1)	LATA Data Output Register						-xxx xxxx	-uuu uuuu
TRISA	—	TRISA6(1)	PORTA Data Direction Register						-111 1111	-111 1111
ADCON1	—	—	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0	--00 0000	--00 0000

Legend: x = unknown, u = unchanged, — = unimplemented locations read as '0'.
Shaded cells are not used by PORTA.

Note 1: RA6 and associated bits are configured as port pins in RCIO and ECIO Oscillator modes only and read '0' in all other oscillator modes.

TABLE 10-17: PORTJ FUNCTIONS

Name	Bit#	Buffer Type	Function
RJ0/ALE	bit 0	ST	Input/output port pin or address latch enable control for external memory interface.
RJ1/$\overline{OE}$	bit 1	ST	Input/output port pin or output enable control for external memory interface.
RJ2/$\overline{WRL}$	bit 2	ST	Input/output port pin or write low byte control for external memory interface.
RJ3/$\overline{WRH}$	bit 3	ST	Input/output port pin or write high byte control for external memory interface.
RJ4/BA0	bit 4	ST	Input/output port pin or byte address 0 control for external memory interface.
RJ5/$\overline{CE}$	bit 5	ST	Input/output port pin or chip enable control for external memory interface.
RJ6/$\overline{LB}$	bit 6	ST	Input/output port pin or lower byte select control for external memory interface.
RJ7/$\overline{UB}$	bit 7	ST	Input/output port pin or upper byte select control for external memory interface.

Legend: ST = Schmitt Trigger input

TABLE 10-18: SUMMARY OF REGISTERS ASSOCIATED WITH PORTJ

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
PORTJ	Read PORTJ pin/Write PORTJ Data Latch								xxxx xxxx	uuuu uuuu
LATJ	LATJ Data Output Register								xxxx xxxx	uuuu uuuu
TRISJ	Data Direction Control Register for PORTJ								1111 1111	1111 1111

Legend: x = unknown, u = unchanged

12.0 TIMER1 MODULE

The Timer1 module timer/counter has the following features:

- 16-bit timer/counter
  (two 8-bit registers: TMR1H and TMR1L)
- Readable and writable (both registers)
- Internal or external clock select
- Interrupt-on-overflow from FFFFh to 0000h
- Reset from ECCP module special event trigger

Figure 12-1 is a simplified block diagram of the Timer1 module.

Register 12-1 details the Timer1 Control register. This register controls the operating mode of the Timer1 module and contains the Timer1 oscillator enable bit (T1OSCEN). Timer1 can be enabled or disabled by setting or clearing control bit, TMR1ON (T1CON<0>).

Timer1 can also be used to provide Real-Time Clock (RTC) functionality to applications with only a minimal addition of external components and code overhead.

REGISTER 12-1: T1CON: TIMER1 CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
RD16	—	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON
bit 7							bit 0

bit 7 **RD16:** 16-bit Read/Write Mode Enable bit
1 = Enables register read/write of Timer1 in one 16-bit operation
0 = Enables register read/write of Timer1 in two 8-bit operations

bit 6 **Unimplemented:** Read as '0'

bit 5-4 **T1CKPS1:T1CKPS0**: Timer1 Input Clock Prescale Select bits
11 = 1:8 Prescale value
10 = 1:4 Prescale value
01 = 1:2 Prescale value
00 = 1:1 Prescale value

bit 3 **T1OSCEN:** Timer1 Oscillator Enable bit
1 = Timer1 oscillator is enabled
0 = Timer1 oscillator is shut off
The oscillator inverter and feedback resistor are turned off to eliminate power drain.

bit 2 **T1SYNC:** Timer1 External Clock Input Synchronization Select bit
When TMR1CS = 1:
1 = Do not synchronize external clock input
0 = Synchronize external clock input
When TMR1CS = 0:
This bit is ignored. Timer1 uses the internal clock when TMR1CS = 0.

bit 1 **TMR1CS:** Timer1 Clock Source Select bit
1 = External clock from pin RC0/T1OSO/T13CKI (on the rising edge)
0 = Internal clock (FOSC/4)

bit 0 **TMR1ON:** Timer1 On bit
1 = Enables Timer1
0 = Stops Timer1

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

13.0 TIMER2 MODULE

The Timer2 module timer has the following features:

- 8-bit timer (TMR2 register)
- 8-bit period register (PR2)
- Readable and writable (both registers)
- Software programmable prescaler (1:1, 1:4, 1:16)
- Software programmable postscaler (1:1 to 1:16)
- Interrupt on TMR2 match of PR2
- MSSP module optional use of TMR2 output to generate clock shift

Timer2 has a control register shown in Register 13-1. Timer2 can be shut off by clearing control bit TMR2ON (T2CON<2>) to minimize power consumption. Figure 13-1 is a simplified block diagram of the Timer2 module. Register 13-1 shows the Timer2 Control register. The prescaler and postscaler selection of Timer2 are controlled by this register.

13.1 Timer2 Operation

Timer2 can be used as the PWM time base for the PWM mode of the ECCP module. The TMR2 register is readable and writable and is cleared on any device Reset. The input clock (FOSC/4) has a prescale option of 1:1, 1:4 or 1:16, selected by control bits T2CKPS1:T2CKPS0 (T2CON<1:0>). The match output of TMR2 goes through a 4-bit postscaler (which gives a 1:1 to 1:16 scaling inclusive) to generate a TMR2 interrupt, latched in flag bit TMR2IF (PIR1<1>).

The prescaler and postscaler counters are cleared when any of the following occurs:

- a write to the TMR2 register
- a write to the T2CON register
- any device Reset (Power-on Reset, $\overline{\text{MCLR}}$ Reset, Watchdog Timer Reset, or Brown-out Reset)

TMR2 is not cleared when T2CON is written.

REGISTER 13-1: T2CON: TIMER2 CONTROL REGISTER

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	T2OUTPS3	T2OUTPS2	T2OUTPS1	T2OUTPS0	TMR2ON	T2CKPS1	T2CKPS0
bit 7							bit 0

bit 7 **Unimplemented:** Read as '0'

bit 6-3 **T2OUTPS3:T2OUTPS0**: Timer2 Output Postscale Select bits
0000 = 1:1 Postscale
0001 = 1:2 Postscale
•
•
•
1111 = 1:16 Postscale

bit 2 **TMR2ON**: Timer2 On bit
1 = Timer2 is on
0 = Timer2 is off

bit 1-0 **T2CKPS1:T2CKPS0**: Timer2 Clock Prescale Select bits
00 = Prescaler is 1
01 = Prescaler is 4
1x = Prescaler is 16

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

TABLE 17-2: PIN CONFIGURATIONS FOR ECCP2

ECCP Mode	CCP2CON Configuration	RB3	RC1	RE7	RE2	RE1	RE0
All devices, CCP2MX = 1, Microcontroller mode:							
Compatible CCP	00xx 11xx	RB3/INT3	ECCP2	RE7	RE2	RE1	RE0
Dual PWM	10xx 11xx	RB3/INT3	P2A	RE7	P2B	RE1	RE0
Quad PWM	x1xx 11xx	RB3/INT3	P2A	RE7	P2B	P2C	P2D
All devices, CCP2MX = 0, Microcontroller mode:							
Compatible CCP	00xx 11xx	RB3/INT3	RC1/T1OS1	ECCP2	RE2	RE1	RE0
Dual PWM	10xx 11xx	RB3/INT3	RC1/T1OS1	P2A	P2B	RE1	RE0
Quad PWM	x1xx 11xx	RB3/INT3	RC1/T1OS1	P2A	P2B	P2C	P2D
PIC18F8525/8621 devices, CCP2MX = 0, all other Program Memory modes:							
Compatible CCP	00xx 11xx	ECCP2	RC1/T1OS1	RE7/AD15	RE2/$\overline{CS}$	RE1/$\overline{WR}$	RE0/$\overline{RD}$
Dual PWM	10xx 11xx	P2A	RC1/T1OS1	RE7/AD15	P2B	RE1/$\overline{WR}$	RE0/$\overline{RD}$
Quad PWM	x1xx 11xx	P2A	RC1/T1OS1	RE7/AD15	P2B	P2C	P2D

Legend: x = Don't care. Shaded cells indicate pin assignments not used by ECCP2 in a given mode.

TABLE 17-3: PIN CONFIGURATIONS FOR ECCP3

ECCP Mode	CCP3CON Configuration	RG0	RE4	RE3	RG3	RH5	RH4
All PIC18F6525/6621 devices:							
Compatible CCP	00xx 11xx	ECCP3	RE4	RE3	RG3/CCP4	N/A	N/A
Dual PWM	10xx 11xx	P3A	P3B	RE3	RG3/CCP4	N/A	N/A
Quad PWM	x1xx 11xx	P3A	P3B	P3C	P3D	N/A	N/A
PIC18F8525/8621 devices, ECCPMX = 1, Microcontroller mode:							
Compatible CCP	00xx 11xx	ECCP3	RE4/AD12	RE3/AD11	RG3/CCP4	RH5/AN13	RH4/AN12
Dual PWM	10xx 11xx	P3A	P3B	RE3/AD11	RG3/CCP4	RH5/AN13	RH4/AN12
Quad PWM	x1xx 11xx	P3A	P3B	P3C	P3D	RH5/AN13	RH4/AN12
PIC18F8525/8621 devices, ECCPMX = 0, Microcontroller mode:							
Compatible CCP	00xx 11xx	ECCP3	RE6/AD14	RE5/AD13	RG3/CCP4	RH7/AN15	RH6/AN14
Dual PWM	10xx 11xx	P3A	RE6/AD14	RE5/AD13	RG3/CCP4	P3B	RH6/AN14
Quad PWM	x1xx 11xx	P3A	RE6/AD14	RE5/AD13	P3D	P3B	P3C
PIC18F8525/8621 devices, ECCPMX = 1, all other Program Memory modes:							
Compatible CCP	00xx 11xx	ECCP3	RE6/AD14	RE5/AD13	RG3/CCP4	RH7/AN15	RH6/AN14

Legend: x = Don't care, N/A = Not available. Shaded cells indicate pin assignments not used by ECCP3 in a given mode.

Note 1: With ECCP3 in Quad PWM mode, CCP4's output is overridden by P1D; otherwise CCP4 is fully operational.

18.4.6 MASTER MODE

Master mode is enabled by setting and clearing the appropriate SSPM bits in SSPCON1 and by setting the SSPEN bit. In Master mode, the SCL and SDA lines are manipulated by the MSSP hardware.

Master mode of operation is supported by interrupt generation on the detection of the Start and Stop conditions. The Stop (P) and Start (S) bits are cleared from a Reset or when the MSSP module is disabled. Control of the I^2C bus may be taken when the P bit is set or the bus is Idle, with both the S and P bits clear.

In Firmware Controlled Master mode, user code conducts all I^2C bus operations based on Start and Stop bit conditions.

Once Master mode is enabled, the user has six options.

1. Assert a Start condition on SDA and SCL.
2. Assert a Repeated Start condition on SDA and SCL.
3. Write to the SSPBUF register initiating transmission of data/address.
4. Configure the I^2C port to receive data.
5. Generate an Acknowledge condition at the end of a received byte of data.
6. Generate a Stop condition on SDA and SCL.

Note: The MSSP module, when configured in I^2C Master mode, does not allow queueing of events. For instance, the user is not allowed to initiate a Start condition and immediately write the SSPBUF register to initiate transmission before the Start condition is complete. In this case, the SSPBUF will not be written to and the WCOL bit will be set, indicating that a write to the SSPBUF did not occur.

The following events will cause MSSP Interrupt Flag bit, SSPIF, to be set (MSSP interrupt, if enabled):

- Start condition
- Stop condition
- Data transfer byte transmitted/received
- Acknowledge transmit
- Repeated Start

FIGURE 18-16: MSSP BLOCK DIAGRAM (I^2C™ MASTER MODE)

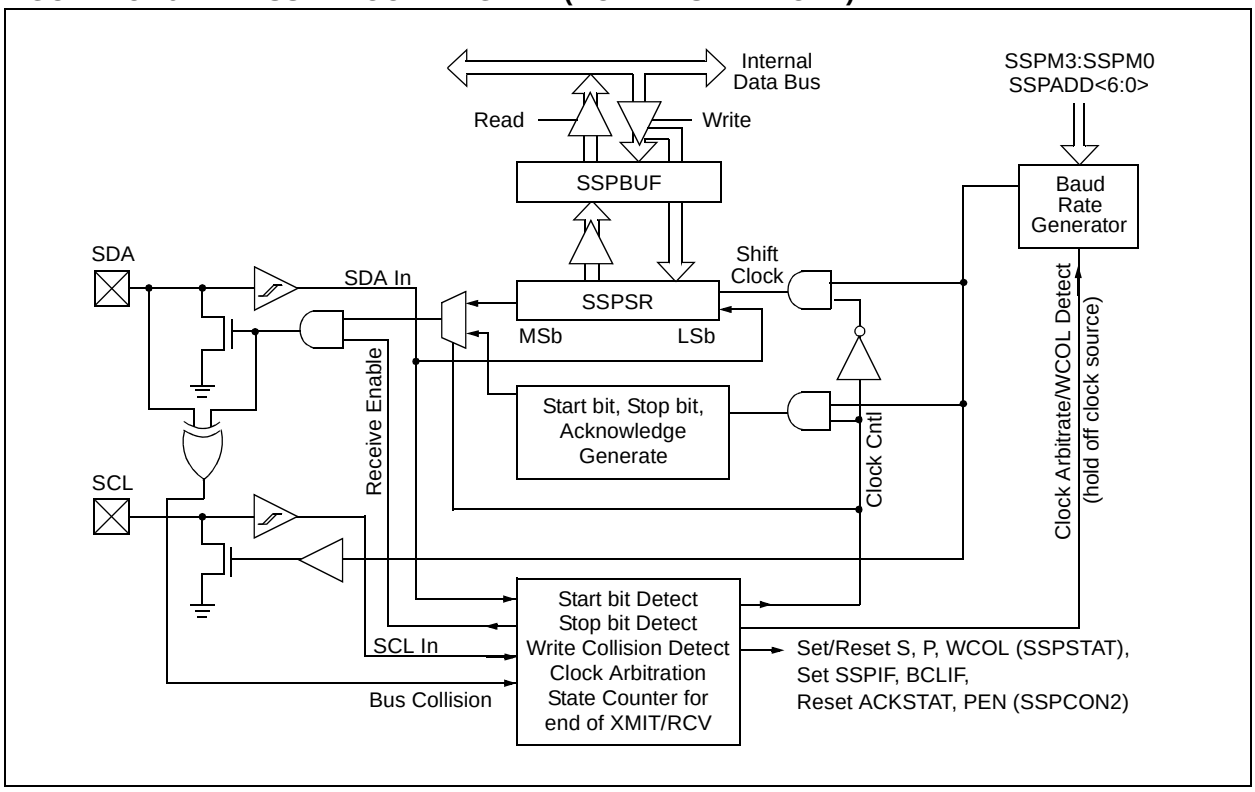

TABLE 18-4: REGISTERS ASSOCIATED WITH I²C™ OPERATION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	0000 000u
PIR1	PSPIF(1)	ADIF	RC1IF	TX1IF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
PIE1	PSPIE(1)	ADIE	RC1IE	TX1IE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
IPR1	PSPIP(1)	ADIP	RC1IP	TX1IP	SSPIP	CCP1IP	TMR2IP	TMR1IP	1111 1111	1111 1111
TRISC	PORTC Data Direction Register								1111 1111	1111 1111
TRISF	TRISF7	TRISF6	TRISF5	TRISF4	TRISF3	TRISF2	TRISF1	TRISF0	1111 1111	1111 1111
SSPBUF	MSSP Receive Buffer/Transmit Register								xxxx xxxx	uuuu uuuu
SSPADD	MSSP Address Register in I²C Slave mode. MSSP Baud Rate Reload Register in I²C Master mode.								0000 0000	0000 0000
SSPCON1	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
SSPSTAT	SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	0000 0000	0000 0000

Legend: x = unknown, u = unchanged, — = unimplemented, read as '0'. Shaded cells are not used by the MSSP in I²C™ mode.

Note 1: Enabled only in Microcontroller mode for PIC18F8525/8621 devices.

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19.3.2 EUSART SYNCHRONOUS MASTER RECEPTION

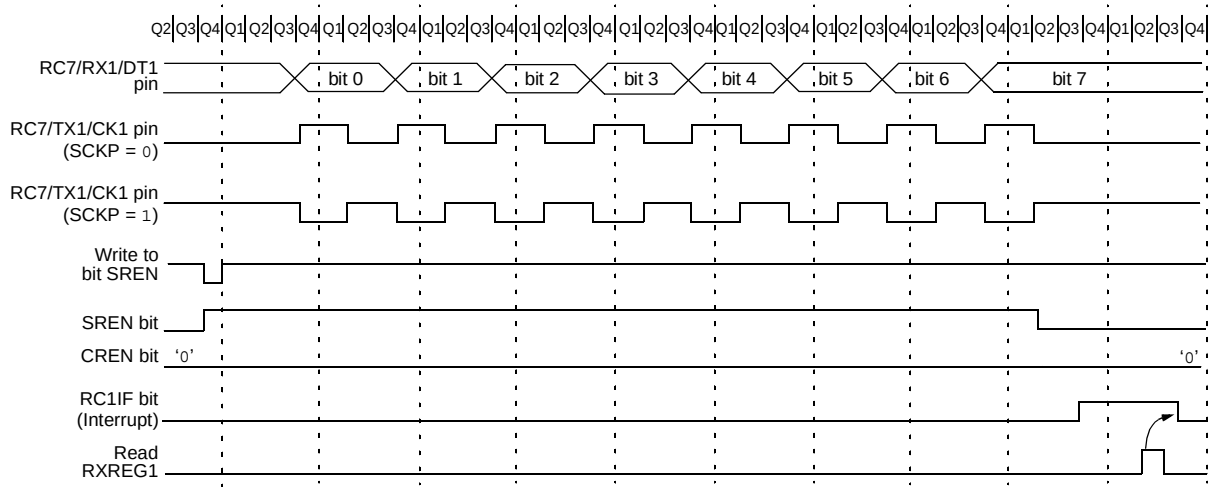
Once Synchronous mode is selected, reception is enabled by setting either the Single Receive Enable bit, SREN (RCSTAx<5>), or the Continuous Receive Enable bit, CREN (RCSTAx<4>). Data is sampled on the RXx pin on the falling edge of the clock.

If enable bit SREN is set, only a single word is received. If enable bit CREN is set, the reception is continuous until CREN is cleared. If both bits are set, then CREN takes precedence.

To set up a Synchronous Master Reception:

1. Initialize the SPBRGHx:SPBRGx registers for the appropriate baud rate. Set or clear the BRG16 bit, as required, to achieve the desired baud rate.
2. Enable the synchronous master serial port by setting bits SYNC, SPEN and CSRC.
3. Ensure bits CREN and SREN are clear.
4. If interrupts are desired, set enable bit RCxIE.
5. If 9-bit reception is desired, set bit RX9.
6. If a single reception is required, set bit SREN. For continuous reception, set bit CREN.
7. Interrupt flag bit RCxIF will be set when reception is complete and an interrupt will be generated if the enable bit RCxIE was set.
8. Read the RCSTAx register to get the 9th bit (if enabled) and determine if any error occurred during reception.
9. Read the 8-bit received data by reading the RCREGx register.
10. If any error occurred, clear the error by clearing bit CREN.
11. If using interrupts, ensure that the GIE and PEIE bits in the INTCON register (INTCON<7:6>) are set.

FIGURE 19-12: SYNCHRONOUS RECEPTION (MASTER MODE, SREN)



Note: Timing diagram demonstrates Sync Master mode with bit SREN = 1 and bit BRGH = 0.

23.0 LOW-VOLTAGE DETECT

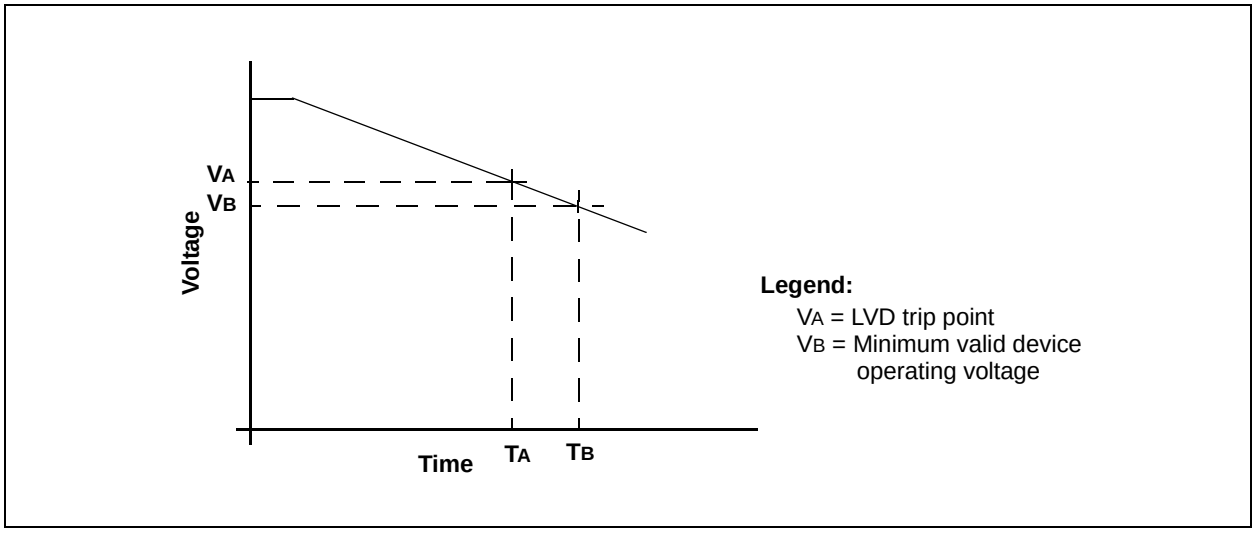
In many applications, the ability to determine if the device voltage (V_{DD}) is below a specified voltage level is a desirable feature. A window of operation for the application can be created, where the application software can do “housekeeping tasks” before the device voltage exits the valid operating range. This can be done using the Low-Voltage Detect module.

This module is a software programmable circuitry, where a device voltage trip point can be specified. When the voltage of the device becomes lower then the specified point, an interrupt flag is set. If the interrupt is enabled, the program execution will branch to the interrupt vector address and the software can then respond to that interrupt source.

The Low-Voltage Detect circuitry is completely under software control. This allows the circuitry to be “turned off” by the software which minimizes the current consumption for the device.

Figure 23-1 shows a possible application voltage curve (typically for batteries). Over time, the device voltage decreases. When the device voltage equals voltage V_A, the LVD logic generates an interrupt. This occurs at time T_A. The application software then has the time, until the device voltage is no longer in valid operating range, to shutdown the system. Voltage point V_B is the minimum valid operating voltage specification. This occurs at time T_B. The difference $T_B - T_A$ is the total time for shutdown.

FIGURE 23-1: TYPICAL LOW-VOLTAGE DETECT APPLICATION



The block diagram for the LVD module is shown in Figure 23-2. A comparator uses an internally generated reference voltage as the set point. When the selected tap output of the device voltage crosses the set point (is lower than), the LVDIF bit is set.

Each node in the resistor divider represents a “trip point” voltage. The “trip point” voltage is the minimum supply voltage level at which the device can operate before the LVD module asserts an interrupt. When the supply voltage is equal to the trip point, the voltage tapped off of the resistor array is equal to the 1.2V internal reference voltage generated by the voltage reference module. The comparator then generates an interrupt signal setting the LVDIF bit. This voltage is software programmable to any one of 16 values (see Figure 23-2). The trip point is selected by programming the LVDL3:LVDL0 bits (LVDCON<3:0>).

NOTES:

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24.3 Power-Down Mode (Sleep)

Power-down mode is entered by executing a SLEEP instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the PD bit (RCON<3>) is cleared, the TO (RCON<4>) bit is set and the oscillator driver is turned off. The I/O ports maintain the status they had before the SLEEP instruction was executed (driving high, low or high-impedance).

For lowest current consumption in this mode, place all I/O pins at either VDD or VSS, ensure no external circuitry is drawing current from the I/O pin, power-down the A/D and disable external clocks. Pull all I/O pins that are high-impedance inputs, high or low externally, to avoid switching currents caused by floating inputs. The T0CKI input should also be at VDD or VSS for lowest current consumption. The contribution from on-chip pull-ups on PORTB should be considered.

The MCLR pin must be at a logic high level (VIHMC).

24.3.1 WAKE-UP FROM SLEEP

The device can wake-up from Sleep through one of the following events:

1. External Reset input on MCLR pin.
2. Watchdog Timer wake-up (if WDT was enabled).
3. Interrupt from INTx pin, RB port change or a peripheral interrupt.

The following peripheral interrupts can wake the device from Sleep:

1. PSP read or write.
2. TMR1 interrupt. Timer1 must be operating as an asynchronous counter.
3. TMR3 interrupt. Timer3 must be operating as an asynchronous counter.
4. CCP Capture mode interrupt (Capture will not occur).
5. MSSP (Start/Stop) bit detect interrupt.
6. MSSP transmit or receive in Slave mode (SPI/I^2C).
7. USART RXx or TXx (Synchronous Slave mode).
8. A/D conversion (when A/D clock source is RC).
9. EEPROM write operation complete.
10. LVD interrupt.

Other peripherals cannot generate interrupts since during Sleep, no on-chip clocks are present.

External MCLR Reset will cause a device Reset. All other events are considered a continuation of program execution and will cause a “wake-up”. The TO and PD bits in the RCON register can be used to determine the cause of the device Reset. The PD bit, which is set on power-up, is cleared when Sleep is invoked. The TO bit is cleared if a WDT time-out occurred (and caused wake-up).

When the SLEEP instruction is being executed, the next instruction (PC + 2) is prefetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt address. In cases where the execution of the instruction following Sleep is not desirable, the user should have a NOP after the SLEEP instruction.

24.3.2 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If an interrupt condition (interrupt flag bit and interrupt enable bits are set) occurs **before** the execution of a SLEEP instruction, the SLEEP instruction will complete as a NOP. Therefore, the WDT and WDT postscaler will not be cleared, the TO bit will not be set and PD bits will not be cleared.
- If the interrupt condition occurs **during or after** the execution of a SLEEP instruction, the device will immediately wake-up from Sleep. The SLEEP instruction will be completely executed before the wake-up. Therefore, the WDT and WDT postscaler will be cleared, the TO bit will be set and the PD bit will be cleared.

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the PD bit. If the PD bit is set, the SLEEP instruction was executed as a NOP.

To ensure that the WDT is cleared, a CLRWDT instruction should be executed before a SLEEP instruction.

POP **Pop Top of Return Stack**

Syntax: [*label*] POP

Operands: None

Operation: (TOS) → bit bucket

Status Affected: None

Encoding:

0000	0000	0000	0110

Description: The TOS value is pulled off the return stack and is discarded. The TOS value then becomes the previous value that was pushed onto the return stack. This instruction is provided to enable the user to properly manage the return stack to incorporate a software stack.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No operation	POP TOS value	No operation

Example:

```
POP
GOTO    NEW
```

Before Instruction
TOS = 0031A2h
Stack (1 level down) = 014332h

After Instruction
TOS = 014332h
PC = NEW

PUSH **Push Top of Return Stack**

Syntax: [*label*] PUSH

Operands: None

Operation: (PC + 2) → TOS

Status Affected: None

Encoding:

0000	0000	0000	0101

Description: The PC + 2 is pushed onto the top of the return stack. The previous TOS value is pushed down on the stack. This instruction allows implementing a software stack by modifying TOS and then pushing it onto the return stack.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	PUSH PC + 2 onto return stack	No operation	No operation

Example:

```
PUSH
```

Before Instruction
TOS = 00345Ah
PC = 000124h

After Instruction
PC = 000126h
TOS = 000126h
Stack (1 level down) = 00345Ah

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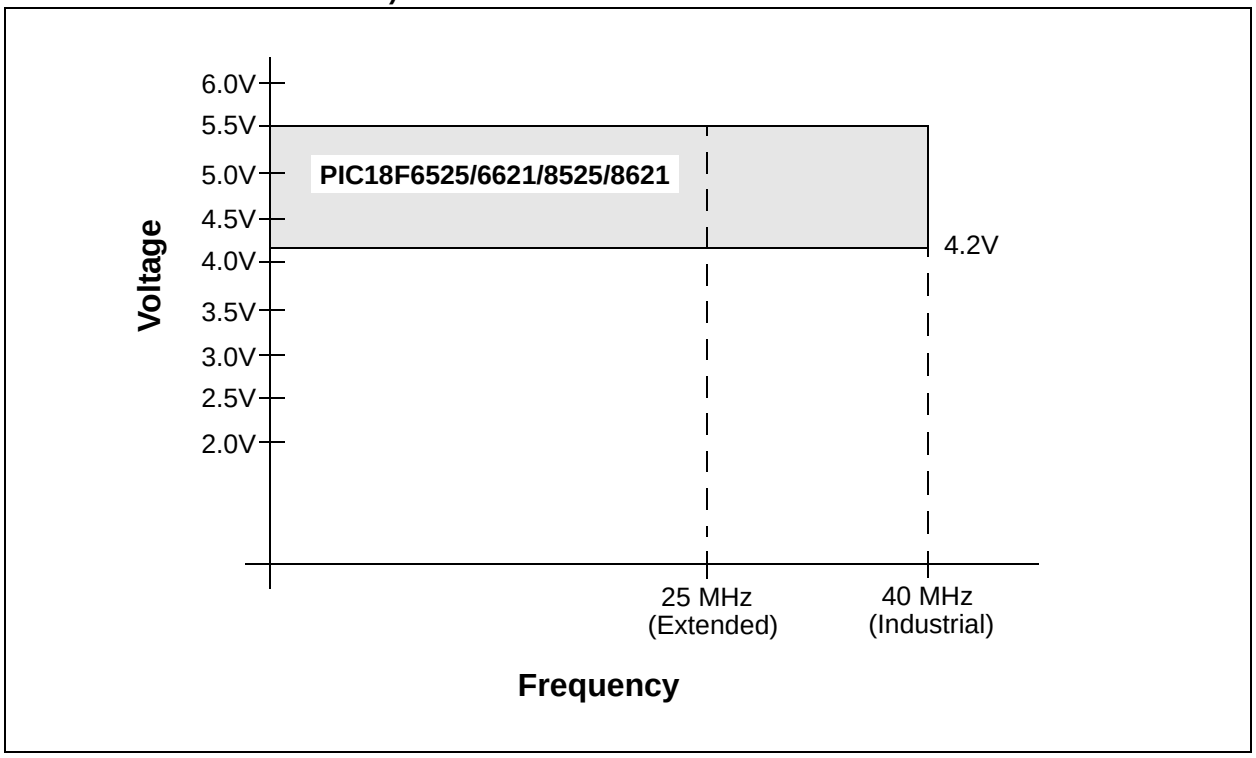
FIGURE 27-1: PIC18F6525/6621/8525/8621 VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL, EXTENDED)



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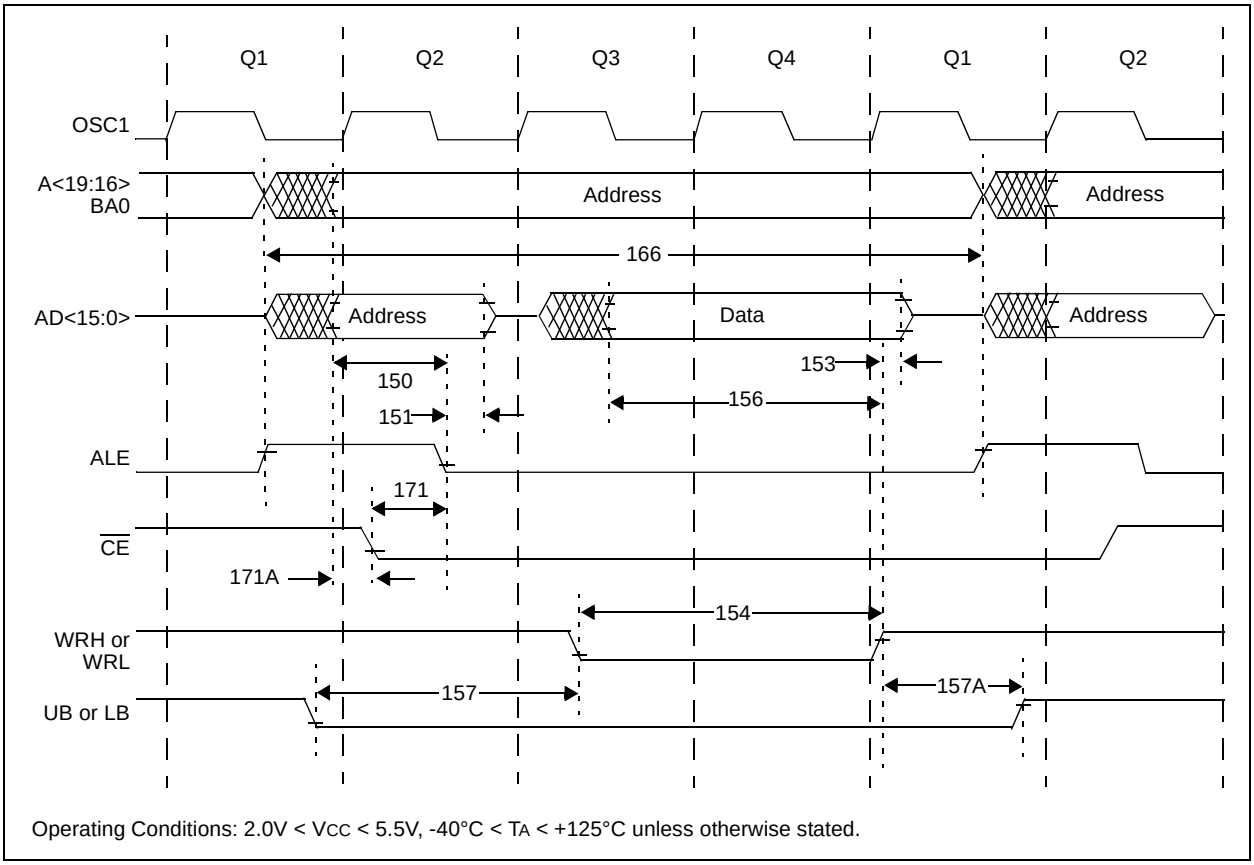
Param. No	Symbol	Characteristics	Min	Typ	Max	Units
167	Tacc	Address Valid to Data Valid	0.75 TCY – 25	—	—	ns
168	Toe	$\overline{OE}$ ↓ to Data Valid		—	0.5 TCY – 25	ns
169	TalL2oeH	ALE ↓ to $\overline{OE}$ ↑	0.625 TCY – 10	—	0.625 TCY + 10	ns
171	TalH2csL	Chip Enable Active to ALE ↓	—	—	10	ns
171A	TubL2oeH	AD Valid to Chip Enable Active	0.25 TCY – 20	—	—	ns

FIGURE 27-8: PROGRAM MEMORY WRITE TIMING DIAGRAM



Operating Conditions: 2.0V < VCC < 5.5V, -40°C < TA < +125°C unless otherwise stated.

TABLE 27-10: PROGRAM MEMORY WRITE TIMING REQUIREMENTS

Param. No	Symbol	Characteristics	Min	Typ	Max	Units
150	TadV2alL	Address Out Valid to ALE ↓ (address setup time)	0.25 TCY – 10	—	—	ns
151	TalL2adl	ALE ↓ to Address Out Invalid (address hold time)	5	—	—	ns
153	TwrH2adl	WRn ↑ to Data Out Invalid (data hold time)	5	—	—	ns
154	TwrL	WRn Pulse Width	0.5 TCY – 5	0.5 TCY	—	ns
156	TadV2wrH	Data Valid before WRn ↑ (data setup time)	0.5 TCY – 10	—	—	ns
157	TbsV2wrL	Byte Select Valid before WRn ↓ (byte select setup time)	0.25 TCY	—	—	ns
157A	TwrH2bsI	WRn ↑ to Byte Select Invalid (byte select hold time)	0.125 TCY – 5	—	—	ns
166	TalH2alH	ALE ↑ to ALE ↑ (cycle time)	—	TCY	—	ns

FIGURE 27-17: EXAMPLE SPI™ SLAVE MODE TIMING (CKE = 1)

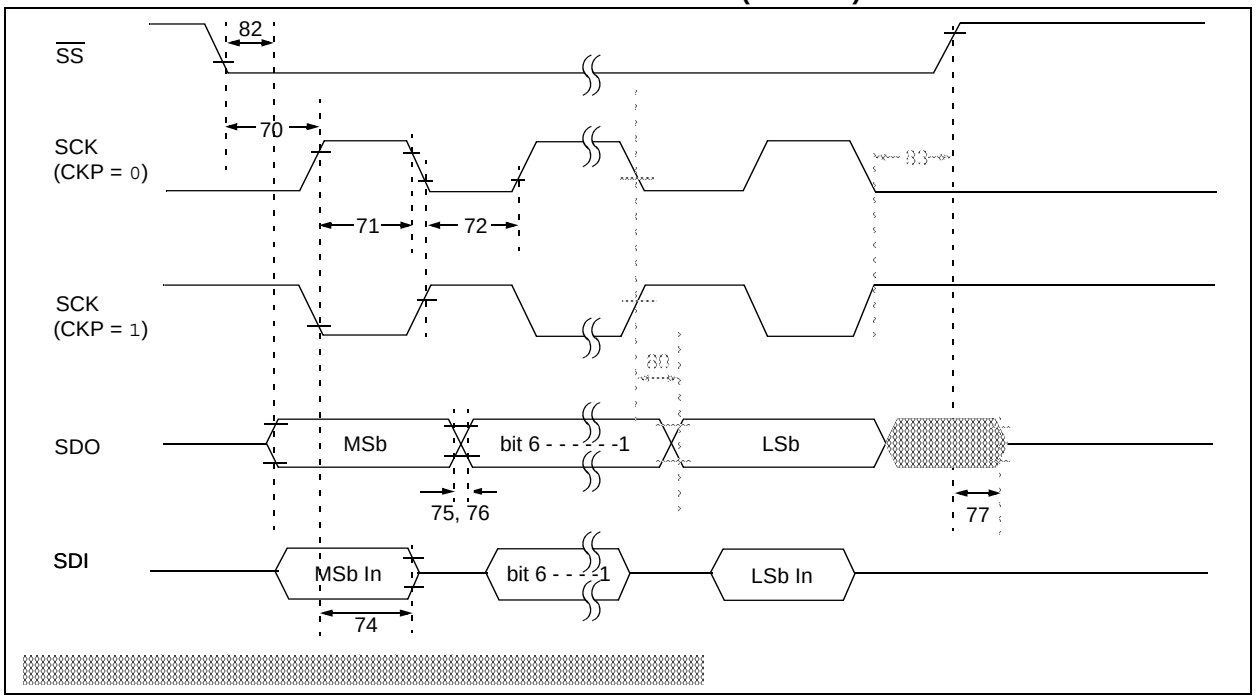


TABLE 27-18: EXAMPLE SPI™ SLAVE MODE REQUIREMENTS (CKE = 1)

Param No.	Symbol	Characteristic		Min	Max	Units	Conditions
70	TssL2scH, TssL2scL	$\overline{SS}$ ↓ to SCK ↓ or SCK ↑ Input		TCY	—	ns	
71	TscH	SCK Input High Time (Slave mode)	Continuous	1.25 TCY + 30	—	ns	
71A			Single Byte	40	—	ns	**(Note 1)**
72	TscL	SCK Input Low Time (Slave mode)	Continuous	1.25 TCY + 30	—	ns	
72A			Single Byte	40	—	ns	**(Note 1)**
73A	TB2B	Last Clock Edge of Byte 1 to the First Clock Edge of Byte 2		1.5 TCY + 40	—	ns	**(Note 2)**
74	TscH2diL, TscL2diL	Hold Time of SDI Data Input to SCK Edge		100	—	ns	
75	TdoR	SDO Data Output Rise Time	PIC18F6525/6621/ 8525/8621	—	25	ns	
			PIC18LF6X2X/8X2X		45	ns	
76	TdoF	SDO Data Output Fall Time		—	25	ns	
77	TssH2doZ	$\overline{SS}$ ↑ to SDO Output High-impedance		10	50	ns	
78	TscR	SCK Output Rise Time (Master mode)	PIC18F6525/6621/ 8525/8621	—	25	ns	
			PIC18LF6X2X/8X2X	—	45	ns	
79	TscF	SCK Output Fall Time (Master mode)		—	25	ns	
80	TscH2doV, TscL2doV	SDO Data Output Valid after SCK Edge	PIC18F6525/6621/ 8525/8621	—	50	ns	
			PIC18LF6X2X/8X2X	—	100	ns	

Note 1: Requires the use of Parameter #73A.
2: Only if Parameter #71A and #72A are used.

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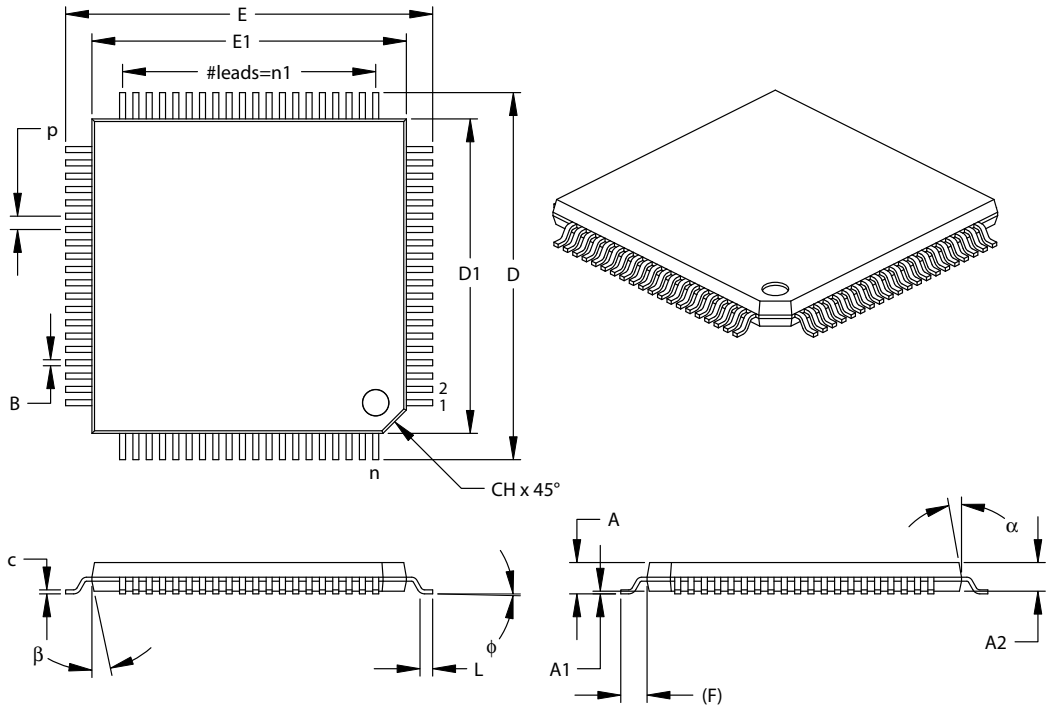
NOTES:

80-Lead Plastic Thin Quad Flatpack (PT) 12x12x1 mm Body, 1.0/0.10 mm Lead Form (TQFP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		80			80	
Pitch	p		.020			0.50	
Pins per Side	n1		20			20	
Overall Height	A	.039	.043	.047	1.00	1.10	1.20
Molded Package Thickness	A2	.037	.039	.041	0.95	1.00	1.05
Standoff	A1	.002	.004	.006	0.05	0.10	0.15
Foot Length	L	.018	.024	.030	0.45	0.60	0.75
Footprint (Reference)	(F)		.039			1.00	
Foot Angle	ϕ	0	3.5	7	0	3.5	7
Overall Width	E	.541	.551	.561	13.75	14.00	14.25
Overall Length	D	.541	.551	.561	13.75	14.00	14.25
Molded Package Width	E1	.463	.472	.482	11.75	12.00	12.25
Molded Package Length	D1	.463	.472	.482	11.75	12.00	12.25
Lead Thickness	c	.004	.006	.008	0.09	0.15	0.20
Lead Width	B	.007	.009	.011	0.17	0.22	0.27
Pin 1 Corner Chamfer	CH	.025	.035	.045	0.64	0.89	1.14
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

*Controlling Parameter

Notes:

Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-026

Drawing No. C04-092

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